

## RoHS Compliance Material Declaration Report

**Company:** Pericom

**Address:** 3545 North First Street,  
San Jose, CA, 95134

**Phone number:** (408) 435 0800

**Date:** 3/12/2007

| Part Detail         |  |                               |              |                        |                              |
|---------------------|--|-------------------------------|--------------|------------------------|------------------------------|
| Pericom Part Number |  | Manufacturer part description | Package Type | Number of Pin/Terminal | Component overall weight (g) |
| PI3A3160ZGE         |  | 3.3V, 0.4-Ohm, Dual SPDT      | TQFN         | 12                     | 0.012221                     |

| RoHS Compliance  |                                  |                                    |
|--|----------------------------------|------------------------------------|
| Is Part compliant to EU RoHS Directive?<br>[1] Yes, [2] Yes with tech exemption*<br>[3] Yes but needs product application exemption*<br>[4] No | RoHS tech exemption [2] details. | Date Component was RoHS Compliant. |
| Yes  | N/A                              | Since Inception                    |

| Content of RoHS restricted materials (g) |         |         |                     |                                |                                      |   |
|--|---------|---------|---------------------|--------------------------------|--------------------------------------|---|
| Lead                                     | Cadmium | Mercury | Hexavalent Chromium | Polybrominated biphenyls (PBB) | Polybrominated Diphenylethers (PBDE) | RoHS restricted substance added intentionally? For what reason? |
| 0  | 0       | 0       | 0                   | 0                              | 0                                    | N/A   |

| Component Soldering Process                                 |                               |   |  |                                     |                          |                             |
|---|-------------------------------|---|--|-------------------------------------|--------------------------|-----------------------------|
| Interconnect Composition, (Metallurgy of the lead/terminal) | JEDEC JEDS97 Pb-free Category | Compatible with a 260C 10s Pb-Free assembly process | Backward compatible with SnPb assembly | Maximum Processing Temperature (°C) | Max Temperature Duration | Max Number of reflow cycles |
| Ni/Pd/Au  | e4                            | Yes   | Yes                                    | 260                                 | 40                       | 3                           |

| Plastics (if applicable) |  |                 |                                |
|--------------------------|--|-----------------|--------------------------------|
| Oxygen Index             | Type of plastic material used in the component | Fire: UL Rating | MSL Level (per JEDEC STD 020C) |
| >28%                     | Epoxy Resin                                    | V-0             | 0                              |

| Tin (Sn) Plating (If Applicable)                  |                            |   |                          |   |                              |
|---|----------------------------|---|--------------------------|---|------------------------------|
| Tin (Sn) Plating – is it Matte (M) or Bright (B)? | Tin (Sn) Plating Thickness | Tin (Sn) plating is there a Nickel (Ni) Barrier? - Yes / No | Nickel Barrier Thickness | If no Nickel barrier is the tin (Sn) termination finish heat treated? | Performed Tin Whisker Test ? |
| N/A   | N/A                        | N/A   | N/A                      | N/A   | N/A                          |

| Bismuth (Bi)                         |
|--------------------------------------|
| Bismuth (Bi) Content (if applicable) |
| 0                                    |